

## DATA ITEM DESCRIPTION

**Title:** Computer Aided Chip Development Data

**Number:** DI-MCCR-80499A

**Approval Date:** 21 NOV 2006

**AMSC Number:** 7645

**Limitation:** N/A

**DTIC Applicable:** No

**GIDEP Applicable:** No

**Office of Primary Responsibility:** NS/I5221

**Applicable Forms:** N/A

### Use/relationship:

Computer Aided Chip Development Data documents fabrication of a chip using computer aids.

This data product is used by the Government to evaluate the reliability of the integrated circuit device produced by the contractor.

This Data Item Description (DID) contains the format and content preparation Instructions for the data product generated by the specific and discrete task requirement as delineated in the contract.

This DID supercedes DI-MCCR-80499.

This DID is related to DI-MCCR-80500A, Computer Aided Cell Development Data.

### Requirements:

1. Reference documents. None.
2. Format and Content:
  - 2.1 The contractor shall prepare and deliver cell development data in accordance with the following:
    - a) The contractor shall utilize and submit the computer aided cell development data on digital media in the following order of preference:
      - i. CD-ROM
      - ii. 8mm Helical Scan Tape
      - iii. 4mm Digital Audio Tape
    - b) The contractor shall utilize electronic media, in accordance with the instructions for digital submissions, for all other documentation and reports.
  - 2.2. Chip description data. This data shall uniquely describe each chip. It

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shall include.

2.2.1. Identification. Chip name and alphanumeric text.

2.2.2. Net list. Cell connectivity data which may be derived from logic description. Note: Net list shall be provided as a simulation model, preferably Verilog or VHDL formats. Other formats shall be considered, with approval at the discretion of the Government Program Manager.

2.3. Chip specification (mechanical). Include bonding pad identification, bonding program, package specifications, labeling instructions, and packing specifications. Note: Format for chip specification (mechanical) data shall be in the form of electronic drawings.

3. END OF DI-MCCR-80499A